

Please Amend Claims 5 and 6 as follows:

1. (Original) A solder joint structure comprising:
 - a patterned conductor containing copper;
 - a solder base section comprising a Sn-Ag-Cu solder material;and
 - a solder joint section comprising a Sn-Zn solder material, the solder joint section being disposed on the solder base section,
 - wherein the solder joint section connects with a terminal of an electronic component by fusion bonding.
2. (Original) The solder joint structure according to claim 1, wherein the Sn-Ag-Cu solder material contains at least one additive selected from the group consisting of antimony, nickel, phosphorus, germanium, and gallium.
3. (Original) A solder joint structure comprising:
 - a patterned conductor containing copper;
 - a solder base section comprising a Sn-Ag solder material containing at least one additive selected from the group consisting of antimony, nickel, phosphorus, germanium, gallium, aluminum, cobalt, chromium, iron, manganese, palladium, and titanium; and
 - a solder joint section comprising a Sn-Zn solder material, the solder joint section being disposed on the solder base section,
 - wherein the solder joint section connects with a terminal of an electronic component by fusion bonding.
4. (Original) A method for soldering an electronic component, the method comprising:
 - (a) forming a first solder land, which is a patterned conductor, containing copper and a second solder land, the first solder land and the second solder land being formed on the same surface of a circuit board;
 - (b) forming a first solder section on each of the first solder land and the second solder land, the first solder section comprising a Sn-Ag-Cu solder material;

(c) mounting a terminal of an electronic component chip on the first solder land;

(d) heating the first solder land and the terminal to connect each other by fusion bonding;

(e) forming a second solder section on the first solder section disposed on the second solder land, the second solder section comprising a Sn-Zn solder material;

(f) inserting a lead terminal of another electronic component into a terminal hole formed near the second solder land; and

(g) heating the second solder section and the lead terminal at a temperature lower than the temperature in step (d) so as to connect the lead terminal to the second solder section by fusion bonding.

5. (Currently Amended) A method for soldering an electronic component, the method comprising:

(a) forming a first solder land, which is a patterned conductor, containing copper and a second solder land, the first solder land and the second solder land being formed on the same surface of a circuit board;

(b) forming a first solder section on each of the first solder land and the second solder land, the first solder section comprising ~~the additive containing Sn-Ag-Cu solder material of claim 2~~ containing at least one additive selected from the group consisting of antimony, nickel, phosphorus, germanium, and gallium;

(c) mounting a terminal of an electronic component chip on the first solder land;

(d) heating the first solder land and the terminal to connect each other by fusion bonding;

(e) forming a second solder section on the first solder section disposed on the second solder land, the second solder section comprising a Sn-Zn solder material;

(f) inserting a lead terminal of another electronic component into a terminal hole formed near the second solder land; and

(g) heating the second solder section and the lead terminal at a temperature lower than ~~the~~a temperature in step (d) so as to connect the lead terminal to the second solder section by fusion bonding.

6. (Currently Amended) A method for soldering an electronic component, the method comprising:

(a) forming a first solder land, which is a patterned conductor, containing copper and a second solder land, the first solder land and the second solder land being formed on the same surface of a circuit board;

(b) forming a first solder section on each of the first solder land and the second solder land, the first solder section comprising ~~the additive-
containing Sn-Ag solder material of claim 3~~containing at least one additive
selected from the group consisting of antimony, nickel, phosphorus,
germanium, gallium, aluminum, cobalt, chromium, iron, manganese,
palladium, and titanium;

(c) mounting a terminal of an electronic component chip on the first solder land;

(d) heating the first solder land and the terminal to connect each other by fusion bonding;

(e) forming a second solder section on the first solder section disposed on the second solder land, the second solder section comprising a Sn-Zn solder material;

(f) inserting a lead terminal of another electronic component into a terminal hole formed near the second solder land; and

(g) heating the second solder section and the lead terminal at a temperature lower than ~~the~~a temperature in step (d) so as to connect the lead terminal to the second solder section by fusion bonding.